ABSTRACT OF THE DISCLOSURE

SEMICONDUCTOR PACKAGE PROCESSING APPARATUS AND CONTROL METHOD THEREOF

A semiconductor package processing apparatus and a control method thereof are disclosed. The semiconductor package processing apparatus includes first package receiving portions to receive a plurality of semiconductor packages therein, second package receiving portions to receive the semiconductor packages, transferred from the first package receiving portions, therein, plural picker units to suck the semiconductor packages received in the first package receiving portions and transfer the semiconductor packages to the second package receiving portions, and a conveying device to transfer the plural picker units individually in a transferring direction of the semiconductor packages.

FIG. 3A

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